

DECLARATION FOR PATENT APPLICATION

As a below named inventor, I hereby declare that:

My residence, post office address, and citizenship are as stated below next to my name;

I believe I am the original, first, and sole inventor (if only one name is listed below) or an original, first, and joint inventor (if plural names are listed below) of the subject matter which is claimed and for which a patent is sought on the invention entitled:

**CONSTRUCTION STRUCTURES AND MANUFACTURING PROCESSES
FOR INTEGRATED CIRCUIT WAFER PROBE CARD ASSEMBLIES**

the specification of which (check one) X is attached hereto, or ___ was filed on _____
as Application Serial No. _____ and was amended on _____ (if applicable).

I hereby state that I have reviewed and understand the contents of the above-identified specification, including the claims, as amended by any amendment referred to above.

I acknowledge the duty to disclose information which is material to the examination of this application in accordance with Title 37, Code of Federal Regulations, Section 1.56(a).

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I hereby claim foreign priority benefits under Title 35, United States Code, Section 119 of any foreign application(s) for patent or inventor's certificate listed below and have also identified below any foreign application for patent or inventor's certificate having a filing date before that of the application on which priority is claimed:

Prior Foreign Application(s)		Priority Claimed	
		Yes	No
PCT/US00/14164	23 May 2000	X	
_____	_____	_____	_____
Number	Country Day/Month/Year Filed		
PCT/US00/21012	28 July 2000	X	
_____	_____	_____	_____
Number	Country Day/Month/Year Filed		

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POWER OF ATTORNEY: As a named inventor, I hereby appoint the following attorney(s) and/or agent(s) to prosecute this application and transact all business in the Patent and Trademark Office connected therewith:

MICHAEL A. GLENN, Reg. No. 30,176
 DONALD M. HENDRICKS, Reg. No. 40,355 (4)
 KIRK D. WONG, Reg. No. 43,284
 CHRISTOPHER PEIL, Reg. No. 45,005

SEND CORRESPONDENCE TO:

GLENN PATENT GROUP 3475 Edison Way, Suite I, Menlo Park, CA 94025
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I hereby claim the benefit under Title 35, United States code, Section 120 of any United States application(s) listed below and, insofar as the subject matter of each of the claims of this application is not disclosed in the prior United States application in the manner provided by the first paragraph of Title 35, United States Code, Section 112, I acknowledge the duty to disclose material information as defined in Title 37, Code of Federal Regulations, Section 1.56(a) which occurred between the filing date of the prior application and the national or PCT international filing date of this application:

60/136,636 5/27/99 PROVISIONAL - Pending
Application Ser. No. Filing Date Status: Patented, Pending, Abandoned

I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment or both, under Section 1001 of Title 18 of the United States Code and that such willful false statements may jeopardize the validity of the application or any patent issued thereon.

1-00
Full name of sole or first inventor: SAMMY MOK
Inventor's signature [Signature] Aug 23, 2001
Residence 106360 E. Estates Drive, Cupertino, CA 95014 CA Date
Post Office Address Same
Citizenship Canadian

2-00
Full name of second joint inventor: FU CHIUNG CHONG
Inventor's signature [Signature] 8/23/01
Residence 19743 Glen Brae Drive, Saratoga, CA 95070 CA Date
Post Office Address Same
Citizenship Malaysia